

<b>STN</b>	<b>Integrované obvody</b> <b>Meranie elektromagnetického vyžarovania</b> <b>Časť 4: Meranie rušení šírených vedením</b> <b>Metóda merania s priamou väzbou 1 ohm/150</b> <b>ohmov</b>	<b>STN</b> <b>EN IEC 61967-4</b>  35 8796
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Integrated circuits - Measurement of electromagnetic emissions - Part 4: Measurement of conducted emissions - 1 /150 direct coupling method

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/21

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**EN IEC 61967-4**

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2021

ICS 31.200

Supersedes EN 61967-4:2002 and all of its amendments  
and corrigenda (if any)

English Version

**Integrated circuits - Measurement of electromagnetic emissions  
- Part 4: Measurement of conducted emissions - 1  $\Omega$ /150  $\Omega$   
direct coupling method  
(IEC 61967-4:2021)**

Circuits intégrés - Mesure des émissions  
électromagnétiques - Partie 4: Mesure des émissions  
conduites - Méthode par couplage direct 1  $\Omega$ /150  $\Omega$   
(IEC 61967-4:2021)

Integrierte Schaltungen - Messung von  
elektromagnetischen Aussendungen - Teil 4: Messung der  
leitungsgeführten Aussendungen - Messung mit direkter 1-  
Ohm-/150-Ohm-Kopplung  
(IEC 61967-4:2021)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels**

**EN IEC 61967-4:2021 (E)****European foreword**

The text of document 47A/1101/CDV, future edition 2 of IEC 61967-4, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61967-4:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-01-20
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-04-20

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

CISPR 16-1-2 NOTE Harmonized as EN 55016-1-2

CISPR 25 NOTE Harmonized as EN 55025

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61000-4-6	-	Electromagnetic compatibility (EMC) - Part 4-6: Testing and measurement techniques - Immunity to conducted disturbances, induced by radio-frequency fields	EN 61000-4-6	-
IEC 61967-1	-	Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions	EN IEC 61967-1	-



IEC 61967-4

Edition 2.0 2021-03

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Integrated circuits – Measurement of electromagnetic emissions –  
Part 4: Measurement of conducted emissions – 1  $\Omega$ /150  $\Omega$  direct coupling  
method**

**Circuits intégrés – Mesure des émissions électromagnétiques –  
Partie 4: Mesure des émissions conduites – Méthode par couplage direct  
1  $\Omega$ /150  $\Omega$**

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Edition 2.0 2021-03

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Integrated circuits – Measurement of electromagnetic emissions –  
Part 4: Measurement of conducted emissions – 1  $\Omega$ /150  $\Omega$  direct coupling  
method**

**Circuits intégrés – Mesure des émissions électromagnétiques –  
Partie 4: Mesure des émissions conduites – Méthode par couplage direct  
1  $\Omega$ /150  $\Omega$**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

#### Part 4: Measurement of conducted emissions – 1 $\Omega$ /150 $\Omega$ direct coupling method

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IEC 61967-4 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition cancels and replaces the first edition published in 2002 and Amendment 1:2006. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) frequency range of 150 kHz to 1 GHz has been deleted from the title;
- b) recommended frequency range for 1  $\Omega$  method has been reduced to 30 MHz;
- c) Annex G with recommendations and guidelines for frequency range extension beyond 1 GHz has been added.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47A/1101/CDV	47A/1107/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts of the IEC 61967 series, under the general title *Integrated circuits – Measurement of electromagnetic emissions* can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

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## INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

### Part 4: Measurement of conducted emissions – 1 $\Omega$ /150 $\Omega$ direct coupling method

#### 1 Scope

This part of IEC 61967 specifies a method to measure the conducted electromagnetic emission (EME) of integrated circuits by direct radio frequency (RF) current measurement with a 1  $\Omega$  resistive probe and RF voltage measurement using a 150  $\Omega$  coupling network. These methods ensure a high degree of reproducibility and correlation of EME measurement results.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61000-4-6, *Electromagnetic compatibility (EMC) – Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields*

IEC 61967-1, *Integrated circuits – Measurement of electromagnetic emissions – Part 1: General conditions and definitions*

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